TOSHIBA Power Transistor Module Silicon Epitaxial Type (Six Darlington Power Transistors in One)

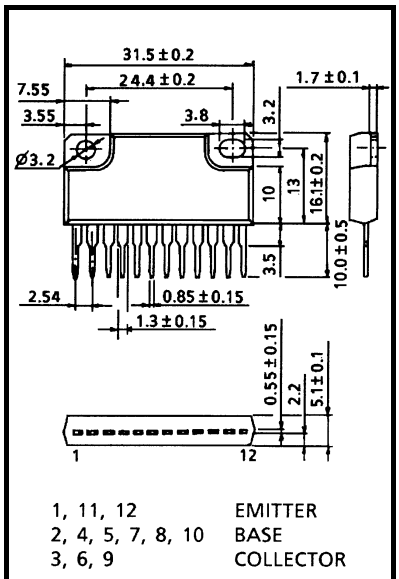
MP6901

Industrial Applications

High Power Switching Applications

Hammer Drive, Pulse Motor Drive and Inductive Load Switching

Unit: mm



JEDEC	—
JEITA	—
TOSHIBA	2-32B1D

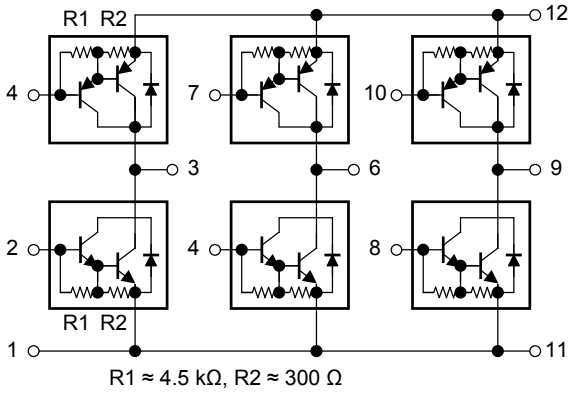
Weight: 6.0 g (typ.)

- Package with heat sink isolated to lead (SIP 12 pins)
- High collector power dissipation (6-device operation)
  : P_T = 5 W (Ta = 25°C)
- High collector current: $I_{C\ (DC)}$ = ±4 A (max)
- High DC current gain: h_{FE} = 2000 (min) (V_{CE} = ±2 V, I_C = ±1 A)

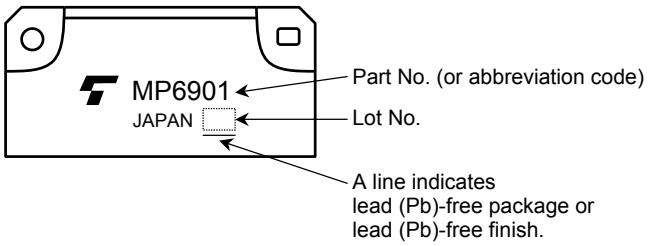
Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating		Unit
			NPN	PNP	
Collector-base voltage		V_{CBO}	100	−100	V
Collector-emitter voltage		V_{CEO}	80	−80	V
Emitter-base voltage		V_{EBO}	5	−5	V
Collector current		I_C	4	−4	A
		I_{CP}	6	−6	
Continuous base current		I_B	0.4	−0.4	A
Collector power dissipation (1-device operation)		P_C	3.0		W
Collector power dissipation (6-device operation)	Ta = 25°C	P_T	5.0		W
	Tc = 25°C		25		
Isolation voltage		V_{Isol}	1000		V
Junction temperature		T_j	150		°C
Storage temperature range		T_{stg}	−55 to 150		°C

Array Configuration



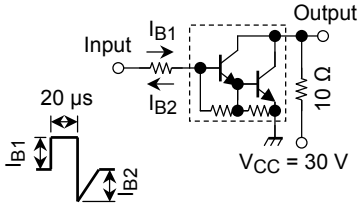
Marking



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance from junction to ambient (6-device operation, Ta = 25°C)	$\Sigma R_{th\ (j\text{-}a)}$	25	°C/W
Thermal resistance from junction to case (6device operation, Tc = 25°C)	$\Sigma R_{th\ (j\text{-}c)}$	5.0	°C/W
Maximum lead temperature for soldering purposes (3.2 mm from case for 10 s)	T_L	260	°C

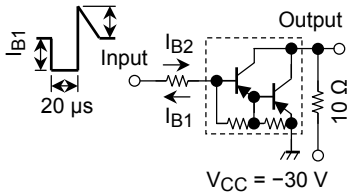
Electrical Characteristics (Ta = 25°C) (NPN transistor)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Collector cut-off current		I_{CBO}	V_{CB} = 100 V, I_E = 0 A	—	—	20	μA
Collector cut-off current		I_{CEO}	V_{CE} = 80 V, I_B = 0 A	—	—	20	μA
Emitter cut-off current		I_{EBO}	V_{EB} = 5 V, I_C = 0 A	0.5	—	2.5	mA
Collector-base breakdown voltage		$V_{(BR)\ CBO}$	I_C = 1 mA, I_E = 0 A	100	—	—	V
Collector-emitter breakdown voltage		$V_{(BR)\ CEO}$	I_C = 10 mA, I_B = 0 A	80	—	—	V
DC current gain		$h_{FE\ (1)}$	V_{CE} = 2 V, I_C = 1 A	2000	—	—	—
		$h_{FE\ (2)}$	V_{CE} = 2 V, I_C = 3 A	1000	—	—	
Saturation voltage	Collector-emitter	$V_{CE\ (sat)}$	I_C = 3 mA, I_B = 6 mA	—	—	1.5	V
	Base-emitter	$V_{BE\ (sat)}$	I_C = 3 mA, I_B = 6 mA	—	—	2.0	
Transition frequency		f_T	V_{CE} = 2 V, I_C = 0.5 A	—	60	—	MHz
Collector output capacitance		C_{ob}	V_{CB} = 10 V, I_E = 0 A, f = 1 MHz	—	35	—	pF
Switching time	Turn-on time	t_{on}		—	0.2	—	μs
	Storage time	t_{stg}		—	1.5	—	
	Fall time	t_f	$I_{B1} = -I_{B2}$ = 6 mA, duty cycle ≤ 1%	—	0.6	—	

Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward current	I_{FM}	—	—	—	4	A
Surge current	I_{FSM}	t = 1 s, 1 shot	—	—	6	A
Forward voltage	V_F	I_F = 1 A, I_B = 0 A	—	—	2.0	V
Reverse recovery time	t_{rr}	I_F = 4 A, V_{BE} = −3 V, dI_F/dt = −50 A/μs	—	1.0	—	μs
Reverse recovery charge	Q_{rr}		—	8	—	μC

Electrical Characteristics (Ta = 25°C) (PNP transistor)

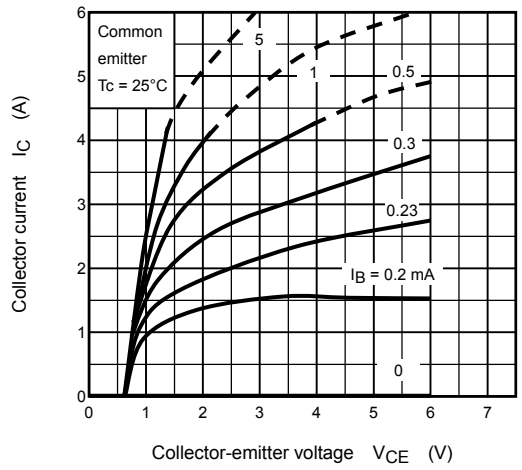
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Collector cut-off current		I_{CBO}	V_{CB} = −100 V, I_E = 0 A	—	—	−20	μA
Collector cut-off current		I_{CEO}	V_{CE} = −80 V, I_B = 0 A	—	—	−20	μA
Emitter cut-off current		I_{EBO}	V_{EB} = −5 V, I_C = 0 A	−0.5	—	−2.5	mA
Collector-base breakdown voltage		$V_{(BR)\ CBO}$	I_C = −1 mA, I_E = 0 A	−100	—	—	V
Collector-emitter breakdown voltage		$V_{(BR)\ CEO}$	I_C = −10 mA, I_B = 0 A	−80	—	—	V
DC current gain		$h_{FE\ (1)}$	V_{CE} = −2 V, I_C = −1 A	2000	—	—	—
		$h_{FE\ (2)}$	V_{CE} = −2 V, I_C = −3 A	1000	—	—	
Saturation voltage	Collector-emitter	$V_{CE\ (sat)}$	I_C = −3 A, I_B = −6 mA	—	—	−1.5	V
	Base-emitter	$V_{BE\ (sat)}$	I_C = −3 A, I_B = −6 mA	—	—	−2.0	
Transition frequency		f_T	V_{CE} = −2 V, I_C = −0.5 A	—	40	—	MHz
Collector output capacitance		C_{ob}	V_{CB} = −10 V, I_E = 0 A, f = 1 MHz	—	60	—	pF
Switching time	Turn-on time	t_{on}		—	0.15	—	μs
	Storage time	t_{stg}		—	0.80	—	
	Fall time	t_f		—	0.40	—	
			$-I_{B1} = I_{B2}$ = 6 mA, duty cycle ≤ 1%				

Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

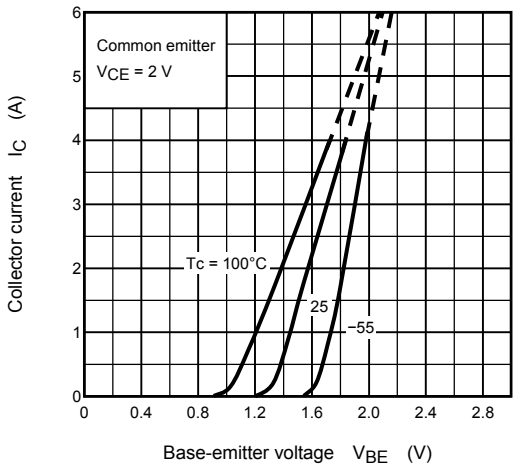
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward current	I_{FM}	—	—	—	4	A
Surge current	I_{FSM}	t = 1 s, 1 shot	—	—	6	A
Forward voltage	V_F	I_F = 1 A, I_B = 0 A	—	—	2.0	V
Reverse recovery time	t_{rr}	I_F = 4 A, V_{BE} = 3 V, dI_F/dt = −50 A/μs	—	1.0	—	μs
Reverse recovery charge	Q_{rr}		—	8	—	μC

(NPN transistor)

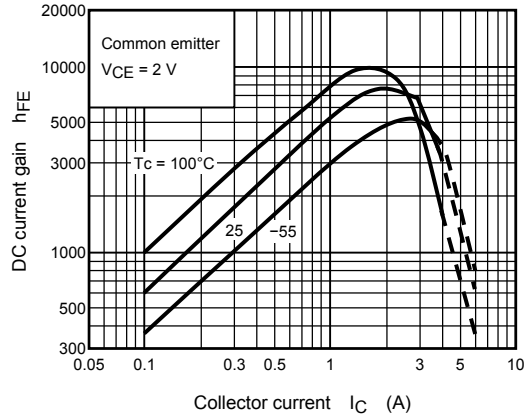
$I_C - V_{CE}$



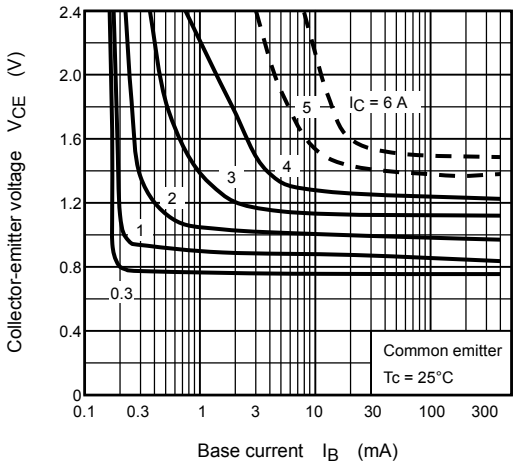
$I_C - V_{BE}$



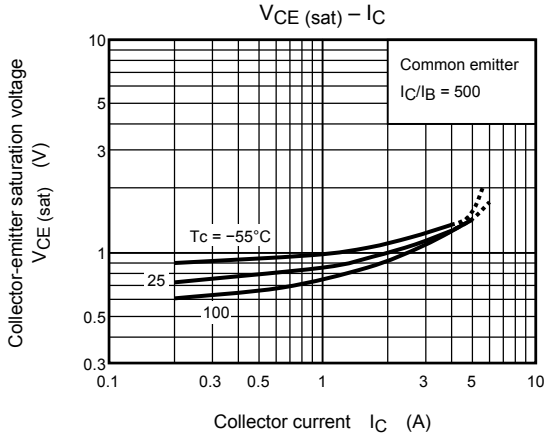
$h_{FE} - I_C$



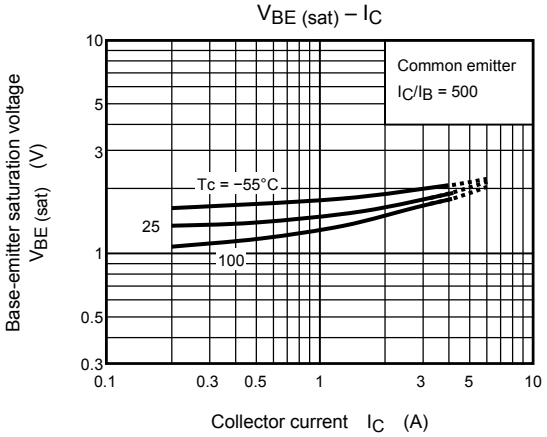
$V_{CE} - I_B$



$V_{CE\ (sat)} - I_C$

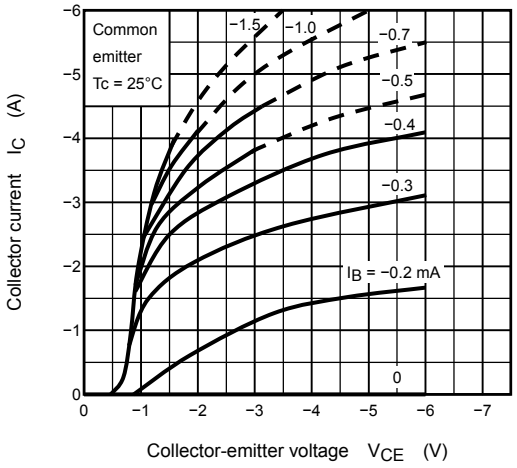


$V_{BE\ (sat)} - I_C$

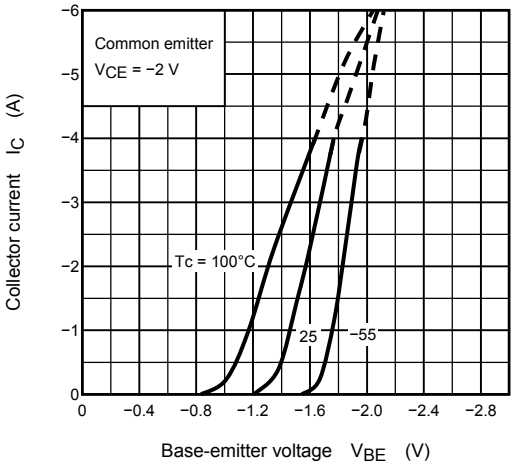


(PNP transistor)

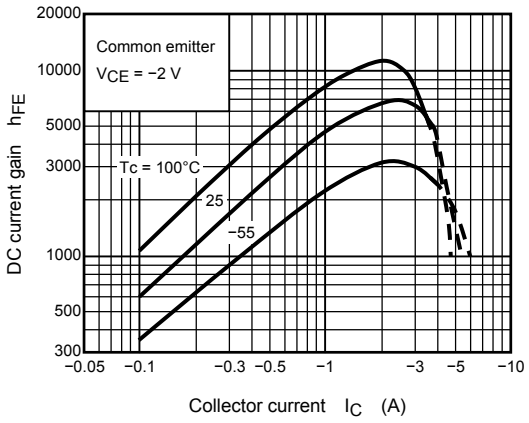
$I_C - V_{CE}$



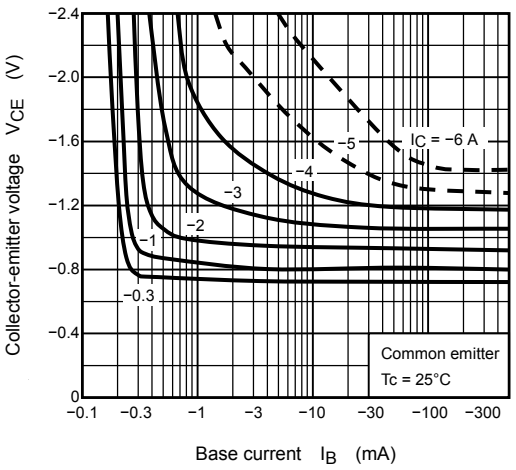
$I_C - V_{BE}$



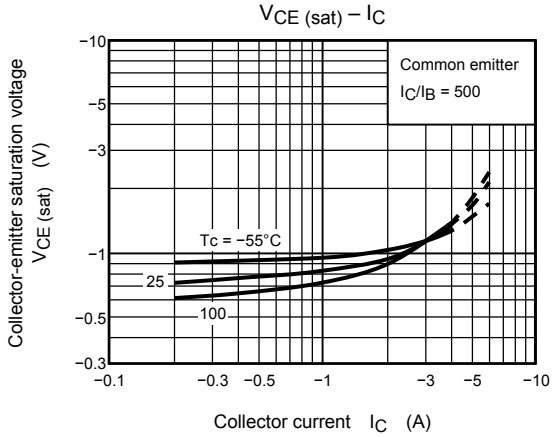
$h_{FE} - I_C$



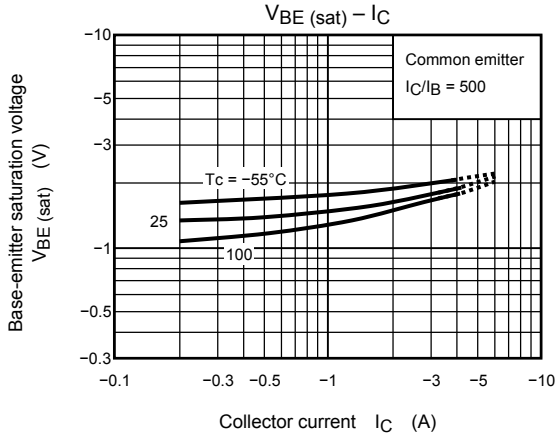
$V_{CE} - I_B$



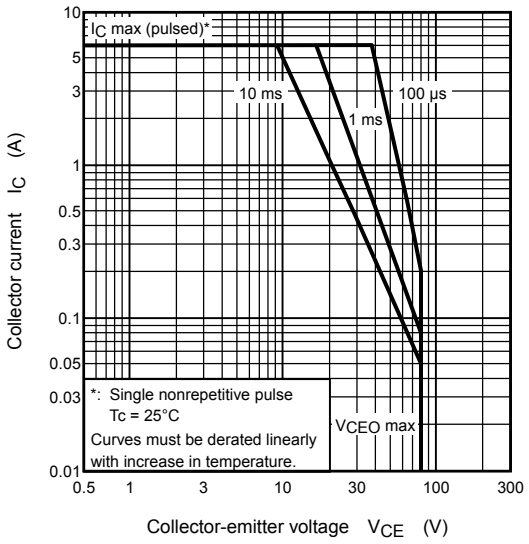
$V_{CE\ (sat)} - I_C$



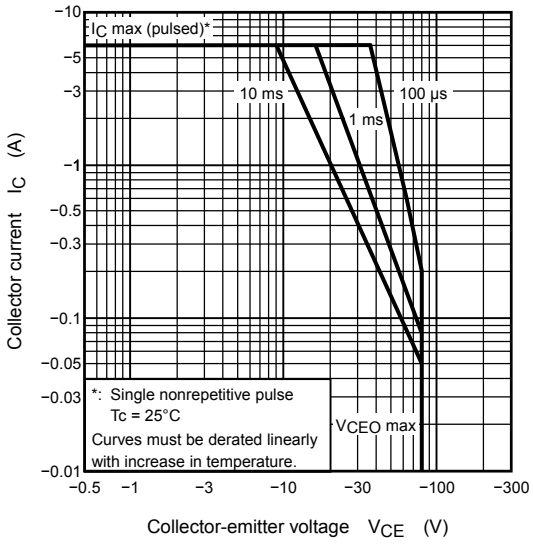
$V_{BE\ (sat)} - I_C$



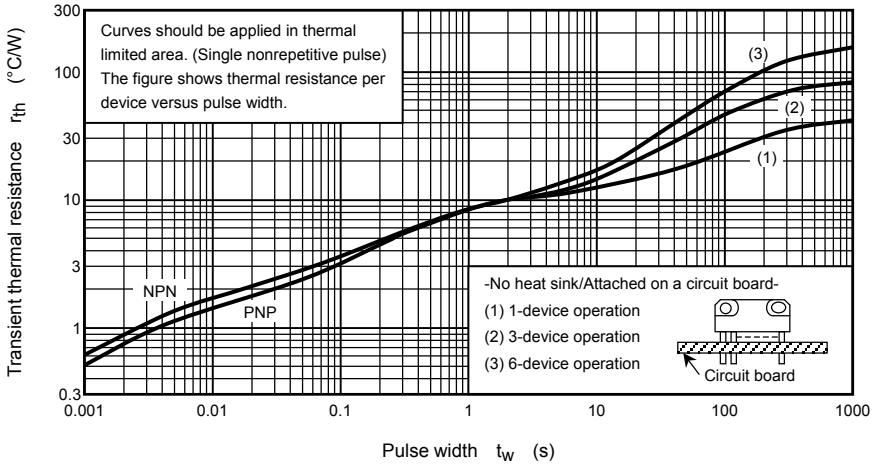
Safe Operating Area (NPN Tr)



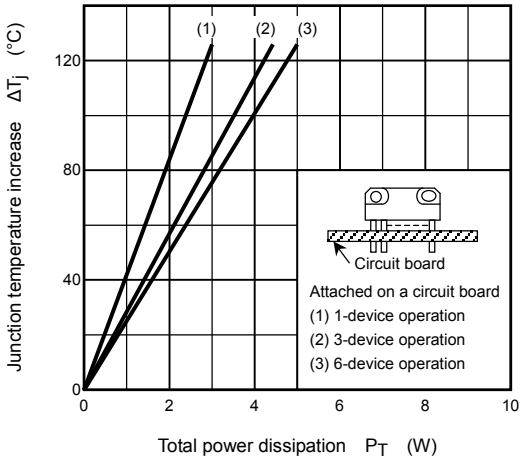
Safe Operating Area (PNP Tr)



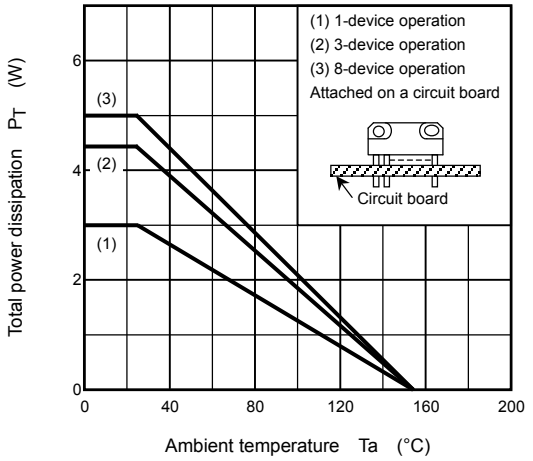
$r_{th} - t_w$



$\Delta T_j - P_T$



$P_T - Ta$



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